506583140 03/30/2021

PATENT ASSIGNMENT COVER SHEET

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NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
BYEONG SEON SON	01/14/2021
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SEON CHAE NA	01/14/2021
JI HWAN KIM	01/14/2021
SANG HOON PARK	01/14/2021
SANG HO KIM	01/14/2021
SEUNG HYUN KIM	01/14/2021

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17217105

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PATENT
REEL: 055768 FRAME: 0454

506583140

ATTORNEY DOCKET NUMBER:	20-2040-US
NAME OF SUBMITTER:	JORI R. FULLER
SIGNATURE:	/Jori R. Fuller/
DATE SIGNED:	03/30/2021

Total Attachments: 3

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> PATENT REEL: 055768 FRAME: 0455

ASSIGNMENT

Case No.: 20-2040-US

Serial No.: 17/217,105

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Date of Execution

of Application: January 14, 2021 Filing Date: March 30, 2021

In consideration of One Dollar (\$1.00) and other good and valuable considerations in hand paid, the receipt and sufficiency whereof are hereby acknowledged, the undersigned hereby assign to:

ASSIGNEE

Name: Hyundai Motor Company

Address: 12, Heolleung-ro, Seocho-gu, Seoul, 06797, Republic of Korea

Name: Kia Motors Corporation

Address: 12, Heolleung-ro, Seocho-gu, Seoul, 06797, Republic of Korea

its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for Letters Patent of the United States, entitled:

TITLE

POWER SUPPLY DEVICE FOR VEHICLE CHILD SEAT

MCDONNELL BOEEDSEN FRILBERT & BERGEOFF LIF BOSCOUTE WALKER DRIVE CHICAGO, BLUNOIS 19808 TILLERIONE (31229) 3-2001

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and identified as:

Case No. 20-2040-US

in the offices of McDonnell Boehnen Hulbert & Berghoff LLP and in said application and any and all other applications, both United States and foreign, which the undersigned may file, either solely or jointly with others, on said invention or improvements, and in any and all Letters Patent of the United States and foreign countries, which may be obtained on any of said applications, and in any reissue or extension of such patents, and further assigns to said assignee the priority right provided by the International Convention.

The undersigned hereby authorize and request the Commissioner of Patents and Trademarks to issue said Letters Patent to said assignee.

The undersigned hereby authorize and request the attorneys of record in said application to insert in this assignment the filing date and serial number of said application when officially known, and the date of execution of the application.

The undersigned warrant themselves to be the owners of the entire right, title and interest in said invention or improvements and to have the right to make this assignment, and further warrant that there are no outstanding prior assignments, licenses, or other encumbrances on the interest herein assigned.

For said considerations the undersigned hereby agree, upon the request and at the expense of said assignee, its successors and assigns, to execute any and all divisional, continuation and substitute applications for said invention or improvements, and any necessary oath, affidavit or declaration relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon said application and any and all applications and other documents for Letters Patent in foreign countries on said invention or improvements, that said assignee, its successors or assigns may deem necessary or expedient, and for the said considerations the undersigned authorize said assignee to apply for patents for said invention or improvements in its own name in such countries where such procedure is proper and further agree, upon the request of said assignee, its successors and assigns, to cooperate to the best of the ability of the undersigned with said assignee, its successors and assigns, in any proceedings or transactions involving such applications or patents, including the preparation and execution of preliminary statements, giving and producing evidence, and performing any and all other acts necessary to obtain, maintain and enforce said Letters Patent, both United States and foreign, and vest all rights therein hereby conveyed in the assignee, its successors and assigns, whereby said Letters Patent will be held and enjoyed by the said assignee, its successors and assigns, to the full end of the term for which said Letters Patent will be granted, as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment had not been made.

Signature: Name:	王 号 セ SON, Byeong Seon	Date: January 14, 202
Signature: Name:	S M & LEE, Tae Hoon	Date: January 14, 202

MCDONDELL BOEINEN HURRET & BENGHOFF UP BOSGLIH WACKER DRIVE CHICAGO, HUNOIS 6006 TELEPHORE (HU) 913-001

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